

# **Final Product Change Notification**

# 202306018F01 : Design Update TJA1128

**Note:** This notice is NXP Company Proprietary.

Issue Date: Jun 29, 2023 Effective date: Sep 27, 2023

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#### Management summary

The TJA1128xTK/0 will be replaced by the TJA1128xTK/1

### Change Category

| [ ]Wafer<br>Fab<br>Process   | []Assembly<br>Process   | []Product Marking           | []Test<br>Process   | [X]Design                              |
|------------------------------|-------------------------|-----------------------------|---------------------|----------------------------------------|
| [ ]Wafer<br>Fab<br>Materials | []Assembly<br>Materials | []Mechanical Specification  | []Test<br>Equipment | []Errata                               |
| [ ]Wafer<br>Fab<br>Location  | []Assembly<br>Location  | []Packing/Shipping/Labeling | []Test<br>Location  | []Electrical<br>spec./Test<br>coverage |
|                              |                         |                             |                     |                                        |

[]Firmware []Other

# PCN Overview Description

NXP has released a drop-in replacement for the TJA1128xTK/0. The replacement can be done without any changes in the customer's application hard- or software.

Details of the change are in the attachment to this PCN.

The present TJA1128xTK/0 will not be discontinued.

A PPAP and samples of the TJA1128xTK/1 are available on request. The information supplied with this PCN should enable customers to transition to the new TJA1128xTK/1 with only, if any, a minor delta qualification.

#### Reason

The presently released TJA1128xTK/0 shows yield loss at both -40°C as well as at +125°C, at final test. All TJA1128xTK/0 products that are delivered to customers are fulfilling the specification as published in the datasheet.

For all PL IVN products, in volume production, wafer testing is done at +125°C, final testing is done at +25°C. The use of tighter guard band limits ensures the behavior over the full temperature range.

The yield loss we experience prevents PL IVN from testing the TJA1128xTK/0 only in the mentioned conditions: wafer testing at +125°C, final testing at +25°C.

The additional testing, final test at cold and hot, takes significant test time. In the present supply situation this may limit the amounts we can deliver to customers.

The minor changes we implemented in the TJA1128xTK/1 will enable us to standardize for this device on wafer testing at +125°C and final testing at +25°C.

When customers do change to the new TJA1128xTK/1, that will free up tester capacity, which will also benefit them in the present, tight, supply situation.

Additional to the above change, we have also used the most recent design rules in this new die. A visible change thereof is the use of orthogonal bond pads, instead of rectangular ones. **Identification of Affected Products** Top Side Marking

### **Product Availability**

Sample Information Samples are available upon request Production Planned first shipmentSep 12, 2023 Anticipated Impact on Form, Fit, Function, Reliability or Quality

See above under heading 'Description of Change'. Disposition of Old Products Existing inventory will be shipped until depleted Additional information

Self qualification:<u>view online</u> Additional documents: <u>view online</u>

## **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 29, 2023.

## Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files':

- An attachment with more detailed description of the change

- An AEC-Q100 reliability results report

- A ZVEI Delta Qualification Matrix (DeQuMa) for the change, both in pdf and zipped excel format

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Quality Account Manager

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